Onsemi

NPN General Purpose Transistor

NST3904F3T5G

The NST3904F3T5G device is a spin-off of our popular SOT-23/SOT-323/SOT-563/SOT-963 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-1123 surface mount package. This device is ideal for low-power surface mount applications where board space is at a premium.

Features

- h_{FE}, 100–300
- Low $V_{CE(sat)}$, $\leq 0.4 \text{ V}$
- Reduces Board Space
- This is a Pb-Free Device

MAXIMUM RATINGS

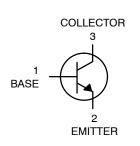
Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V _{CEO}	40	Vdc
Collector - Base Voltage	V _{CBO}	60	Vdc
Emitter – Base Voltage	V _{EBO}	6.0	Vdc
Collector Current – Continuous	۱ _C	200	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation, T _A = 25°C Derate above 25°C	P _D (Note 1)	290 2.3	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 1)	432	°C/W
Total Device Dissipation, T _A = 25°C Derate above 25°C	P _D (Note 2)	347 2.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 2)	360	°C/W
Thermal Resistance, Junction-to-Lead 3	R _{ΨJL} (Note 2)	143	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

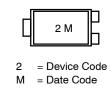
1. 100 mm² 1 oz, copper traces.
 2. 500 mm² 1 oz, copper traces.





MARKING DIAGRAM

STYLE 1



ORDERING INFORMATION

Device	Package	Shipping [†]
NST3904F3T5G	SOT-1123 (Pb-Free)	8000 / Tape & Reel

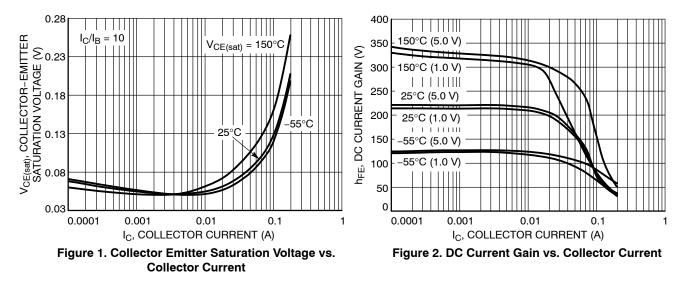
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NST3904F3T5G

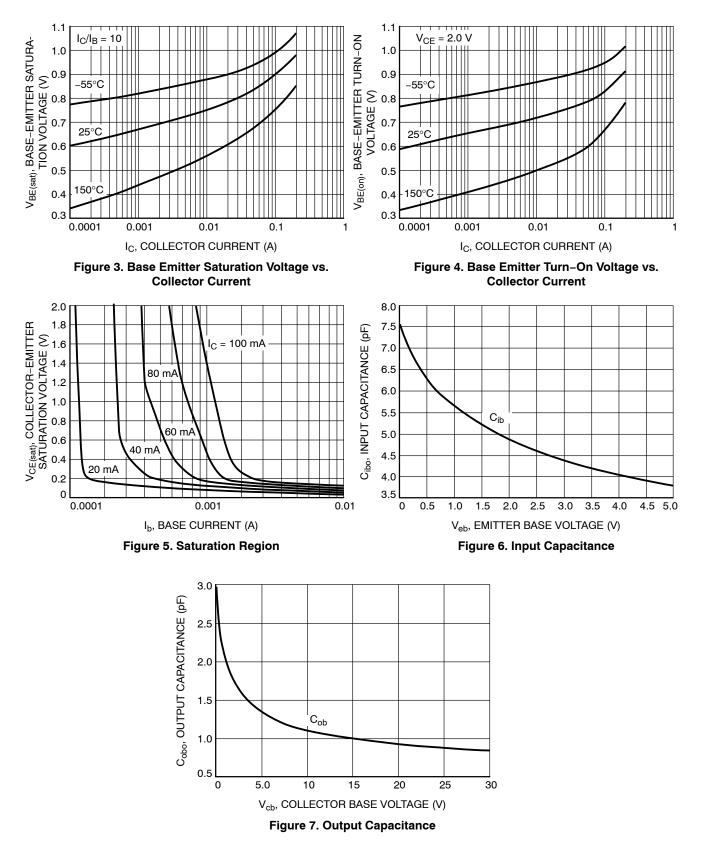
ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

C	Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				•	
Collector - Emitter Breakdown Volt	age (Note 3) (I _C = 1.0 mAdc, I _B = 0)	V _{(BR)CEO}	40	-	Vdc
Collector - Base Breakdown Voltag	e (I _C = 10 μAdc, I _E = 0)	V _{(BR)CBO}	60	-	Vdc
Emitter-Base Breakdown Voltage	$(I_{E} = 10 \ \mu Adc, \ I_{C} = 0)$	V _{(BR)EBO}	6.0	-	Vdc
Collector Cutoff Current ($V_{CE} = 30$	Vdc, V _{EB} = 3.0 Vdc)	I _{CEX}	-	50	nAdc
ON CHARACTERISTICS (Note 3)			L		
$ \begin{array}{l} DC \mbox{ Current Gain} \\ (I_C = 0.1 \mbox{ mAdc}, V_{CE} = 1.0 \mbox{ Vdc}) \\ (I_C = 1.0 \mbox{ mAdc}, V_{CE} = 1.0 \mbox{ Vdc}) \\ (I_C = 10 \mbox{ mAdc}, V_{CE} = 1.0 \mbox{ Vdc}) \\ (I_C = 50 \mbox{ mAdc}, V_{CE} = 1.0 \mbox{ Vdc}) \\ (I_C = 100 \mbox{ mAdc}, V_{CE} = 1.0 \mbox{ Vdc}) \end{array} $		h _{FE}	40 70 100 60 30	- 300 -	_
$\begin{array}{l} \mbox{Collector}-\mbox{Emitter Saturation Volta} \\ (I_C = 10 \mbox{ mAdc}, \mbox{ I}_B = 1.0 \mbox{ mAdc}) \\ (I_C = 50 \mbox{ mAdc}, \mbox{ I}_B = 5.0 \mbox{ mAdc}) \end{array}$	ge	V _{CE(sat)}		0.2 0.3	Vdc
$\begin{array}{l} Base-Emitter \; Saturation \; Voltage \\ (I_{C}=10\; mAdc, \; I_{B}=1.0\; mAdc) \\ (I_{C}=50\; mAdc, \; I_{B}=5.0\; mAdc) \end{array}$		V _{BE(sat)}	0.65	0.85 1.0	Vdc
SMALL-SIGNAL CHARACTERIS	TICS			•	
Current-Gain - Bandwidth Produc	ct (I _C = 10 mAdc, V _{CE} = 20 Vdc, f = 100 MHz)	f _T	200	-	MHz
Output Capacitance (V _{CB} = 5.0 Vd	c, I _E = 0, f = 1.0 MHz)	C _{obo}	-	4.0	pF
Input Capacitance (V _{EB} = 0.5 Vdc,	I _C = 0, f = 1.0 MHz)	C _{ibo}	-	8.0	pF
Noise Figure (V _{CE} = 5.0 Vdc, I _C =	100 μAdc, R _S = 1.0 k Ω, f = 1.0 kHz)	NF	-	5.0	dB
SWITCHING CHARACTERISTICS	3	·			•
Delay Time	(V _{CC} = 3.0 Vdc, V _{BE} = -0.5 Vdc)	t _d	-	35	
Rise Time	(I _C = 10 mAdc, I _{B1} = 1.0 mAdc)	t _r	-	35	ns
Storage Time	(V _{CC} = 3.0 Vdc, I _C = 10 mAdc)	t _s	-	275	
Fall Time	(I _{B1} = I _{B2} = 1.0 mAdc)	t _f	-	50	– ns

3. Fulse lest. Fulse width \leq 500 µs, Duty Cycle \leq 2.0%.



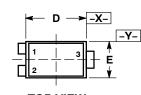
NST3904F3T5G



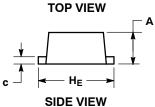


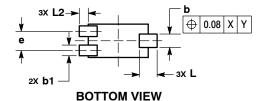


SCALE 8:1

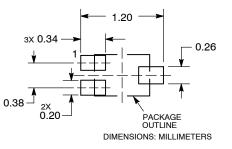


SOT-1123 CASE 524AA ISSUE C





SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLE 1:	STYLE 2:	STYLE 3:	STYLE 4:	STYLE 5:
PIN 1. BASE	PIN 1. ANODE	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. GATE
2. EMITTER	2. N/C	2. ANODE	2. CATHODE	2. SOURCE
3. COLLECTOR	3. CATHODE	3. CATHODE	3. ANODE	3. DRAIN

DOCUMENT NUMBER:	98AON23134D	Electronic versions are uncontrolled except when accessed directly from Printed versions are uncontrolled except when stamped "CONTROLLED	
DESCRIPTION:	SOT-1123, 3-LEAD, 1.0X0	.6X0.37, 0.35P	PAGE 1 OF 1
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DATE 29 NOV 2011

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS.
- CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE
- MINIMUM THICKNESS OF BASE MATERIAL.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.34	0.40	
b	0.15	0.28	
b1	0.10	0.20	
С	0.07	0.17	
D	0.75	0.85	
Е	0.55	0.65	
е	0.35	0.40	
HE	0.95	1.05	
L	0.185 REF		
L2	0.05	0.15	

GENERIC MARKING DIAGRAM*

X = Specific Device Code M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " •", may or may not be present.

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